Product End-of-Life Disassembly Instructions

Product Category: **Servers**

Marketing Name / Model
[List multiple models if applicable.]

HPE ProLiant DL325 Gen10 Plus

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by Directive 2012/19/EU of the European Parliament and of the Council on Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>7</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>0</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Based on the Power Supply</td>
<td>14</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Torx Driver</td>
<td>T10/T15</td>
</tr>
<tr>
<td>Philips Driver</td>
<td>#2</td>
</tr>
<tr>
<td>Flat Head Screw Driver</td>
<td>Medium</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Controller (PCBA) by Torx Driver and dispose properly.
2. Remove Shiner Card/ HDD backplane/ Mother Board (PCBA) by Torx Driver and dispose properly.
3. Remove the top cover and locate the battery on the system board. With a medium flat head screw driver remove the battery and dispose of properly.
4. Remove the top cover and locate the megacell on the system board. Remove the megacell and dispose of properly.
5. Remove Capacitors > 2.5CM of the power supply(s) from the system. With #2 Philips screw driver remove the screws securing the top cover and the heatsinks in the P/S then locate the capacitors and pry from the PCB with a medium flat head screw driver and dispose of properly.
6. Remove the raid card and dispose it properly.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Attachment 1 – Mother Board
Attachment 2 & 3 – Battery Location
Attachment 4 to 15 - Electrolytic Capacitor location in PSU
Attachment 1:

Remove mother board with a surface greater than 10 sq cm

Attachment 2:

Remove Li Battery
Attachment 3:

Remove Mega-cell

Attachment 4:

Remove Electrolytic Capacitors (C201,202: 10mm*38.5mm, C200: 26mm*43mm , C250,251: 13mm*50mm) from power supply HSTNS-PR62.
Attachment 5:

Remove Electrolytic Capacitor (C102: 30mm*60mm and C220/C221:10mm*25mm) from power supply HSTNS-PL62.

Attachment 6:

Remove Electrolytic Capacitor (C102: 30mm*40mm and C217/C218:10mm*25mm) from power supply HSTNS-PL41-1.
Attachment 7:

Remove Electrolytic Capacitor (BC1: 25mm*60 mm and C106/C107/C108 10mm*25mm) from power supply HSTNS-PC41-1 / HSTNS-PC41.

Attachment 8:

Remove Electrolytic Capacitor (C801:25mm*60mm and C237/C238:10mm*25) From power supply HSTNS-PD41-1.
Attachment 9:

Remove Electrolytic Capacitor (C801: 25mm*60mm and C212/C233/C238: 10mm*25mm) from power supply HSTNS-PD44-1.

Attachment 10:

Remove capacitor Electrolytic Capacitor (C102: 30mm*50mm and C217/C218: 10mm*25mm) from power supply HSTNS-PL45-1.
Attachment 11:

Remove capacitor from power supply Flextronics HSTNS-PF46-1.

Attachment 12:

Remove Electrolytic Capacitor (C101, C105, C106, C114, C115: 12.5mm*30mm and C215/C216:10mm*25mm) from power supply HSTNS-PL46-1.
Attachment 13:

Remove Electrolytic Capacitor (C102: 30mm*30mm and C209/C221:10mm*25mm)
From HSTNS-PL40-1, HSTNS-PL40

Attachment 14:

Remove Electrolytic Capacitor (BC1: 25mm*60 mm and C106/C107/C108 10mm*25mm)
from power supply HSTNS-PC40-1 / HSTNS-PC40
Attachment 15:

Remove Electrolytic Capacitors (C801:25mm*60mm and C237,C238:10mm*25mm) from power supply Delta HSTNS-PD40-1.